SN54LV245, SN74LV245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCLS075E - JANUARY 1991 - REVISED APRIL 1996

- EPIC ™ (Enhanced-Performance Implanted CMOS) 2-µ Process
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC}, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 > 2 V at V_{CC}, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs

description

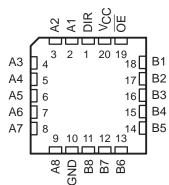
These octal bus transceivers are designed for 2.7-V to 5.5-V V_{CC} operation.

The 'LV245 are designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

SN74LV245 DB, DW, OR PW PACKAGE (TOP VIEW)									
DIR [A1 [A2 [A3 [A4 [A5 [A6 [A8 [GND]	1 2 3 4 5 6 7 8 9 10	20 19 18 17 16 15 14 13 12 11	V _{CC} OE B1 B2 B3 B4 B5 B6 B7 B8						

SN54LV245 ... J OR W PACKAGE

SN54LV245 . . . FK PACKAGE (TOP VIEW)



The SN74LV245 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LV245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LV245 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE								
INP	UTS							
OE	DIR	OPERATION						
L	L	B data to A bus						
L	Н	A data to B bus						
Н	Х	Isolation						



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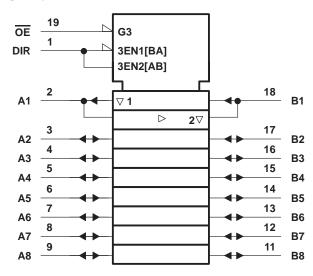


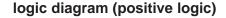
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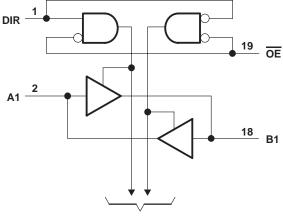
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logic symbol[†]







To Seven Other Channels

⁺ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for DB, DW, J, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V_{CC} $-0.5 \vee to 7 \vee Input voltage range, V_I$: Except I/O ports (see Note 1)I/O ports (see Notes 1 and 2) $-0.5 \vee to V_{CC} + 0.5 \vee I/O = 0.5 \vee to V_{CC} + 0.5 \vee IO = 0.5 \vee to V_{CC} + 0$
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) ±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC}) ±50 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$ ±35 mA
Continuous current through V _{CC} or GND ±70 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DB package
DW package 1.6 W
PW package 0.7 W
Storage temperature range, T _{stg} –65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 7 V maximum.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.



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recommended operating conditions (see Note 4)

				V245	SN74LV245		UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2.7	5.5	2.7	5.5	V
	I Pake Isonal Parasition Items	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		2		
VIH	High-level input voltage	V_{CC} = 4.5 V to 5.5 V	3.15		3.15		V
VIL	Law law Parata strategi	$V_{CC} = 2.7 V \text{ to } 3.6 V$		0.8		0.8	
	Low-level input voltage	V_{CC} = 4.5 V to 5.5 V		1.65		1.65	V
VI	Input voltage		0	Vcc	0	VCC	V
VO	Output voltage		0	VCC	0	VCC	V
	High-level output current	$V_{CC} = 2.7 V \text{ to } 3.6 V$	20	-8		-8	
ЮН		V_{CC} = 4.5 V to 5.5 V	40	-16		-16	mA
	Level and a device a summer of	$V_{CC} = 2.7 V \text{ to } 3.6 V$	Y	8		8	
IOL	Low-level output current	V_{CC} = 4.5 V to 5.5 V		16		16	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		0	50	0	50	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			× +	SN	154LV24	15	SN	UNIT			
		TEST CONDITIONS	v _{cc} †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
		I _{OH} = -100 μA	MIN to MAX	V _{CC} -0	.2		V _{CC} -0	.2			
∨он		I _{OH} = -8 mA	3 V	2.4			2.4			V	
		I _{OH} = -16 mA	4.5 V	3.6			3.6				
		I _{OL} = 100 μA	MIN to MAX			0.2			0.2		
VOL		I _{OL} = 8 mA	3 V			0.4			0.4	V	
-		I _{OL} = 16 mA	4.5 V			\$0.55			0.55		
			3.6 V		ľ.	±1			±1		
lj –		$V_I = V_{CC}$ or GND	5.5 V		P	±1			±1	μA	
. +			3.6 V		2	±5			±5		
loz‡		$V_{O} = V_{CC}$ or GND	5.5 V	ć	5	±5			±5	μA	
			3.6 V	0	4	20			20		
ICC		$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V	Q		20			20	μA	
∆ICC		One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V			500			500	μΑ	
			3.3 V		2.5			2.5			
Ci	Control inputs	$V_I = V_{CC}$ or GND	5 V		3			3		pF	
			3.3 V		7			7		_	
Co	A or B port	$V_{O} = V_{CC}$ or GND	5 V		8			8		pF	

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

 \ddagger For I/O ports, the parameter I_{OZ} includes the input leakage current.



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switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

		то				SN54L	V245				
PARAMETER	PARAMETER (INPUT)		Vcc	= 5 V ± 0).5 V	V _{CC} =	: 3.3 V ±	0.3 V	V _{CC} =	2.7 V	UNIT
		(OUTPUT)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX	
^t pd	A or B	B or A		8	11	N.	8	14	M	18	ns
ten	OE	A or B		6	A 4	e Mile	12	21	N	25	ns
^t dis	OE	A or B		8	16		12	20		24	ns

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

						SN74L	V245				
PARAMETER	FROM (INPUT)	FROM TO (INPUT) (OUTPUT)		$V_{CC} = 5 V \pm 0.5 V$ $V_{CC} = 3.3 V \pm 0.3 V$				0.3 V	V _{CC} = 2.7 V		UNIT
		(001101)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX	
^t pd	A or B	B or A		8	11		8	14		18	ns
ten	OE	A or B		6	14		12	21		25	ns
^t dis	OE	A or B		8	16		12	20		24	ns

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	Vcc	TYP	UNIT	
C _{pd} Power dissipation capac transceiver		Outputs enabled		3.3 V	36	
	Power dissipation capacitance per	Outputs disabled		3.3 V	4	- 5
	transceiver	Outputs enabled	$C_{L} = 50 \text{ pF}, \text{ f} = 10 \text{ MHz}$	5 V	46	pF
		Outputs disabled		5 V	4	



٧z 0 TEST **S**1 O Open **1 k**Ω **S1** From Output Open tPLH/tPHL **Under Test** GND \cap tPLZ/tPZL ٧z GND tPHZ/tPZH $C_L = 50 \text{ pF}$ **1 k**Ω (see Note A) WAVEFORM V_{CC} = 4.5 V $V_{CC} = 2.7 V$ CONDITION to 5.5 V to 3.6 V _ 1.5 V ۷m $0.5 \times V_{CC}$ Vcc 2.7 V ٧i LOAD CIRCUIT $\mathbf{2}\times \mathbf{V_{CC}}$ ٧z 6 V ٧i ٧m **Timing Input** 0 V tw t_{su} th ٧i ٧i ٧m Input ۷m ٧m Data Input ۷m 0 V 0 V **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS** PULSE DURATION SETUP AND HOLD TIMES ٧i Vi Output ۷m ۷m Input ٧m ۷m Control 0 V 0 V ^tPZL ^tPHL ^tPLH tPLZ -Output VOH $0.5 \times V_z$ Waveform 1 ٧m ۷m Output ۷m V_{OL} + 0.3 V S1 at Vz VOL VOL (see Note B) ^tPHZ **t**PLH ^tPHL ^tPZH Output Output VOH ۷он Waveform 2 V_{OH} – 0.3 ٧m ٧m ٧m S1 at GND ≈ 0 V Vol (see Note B) **VOLTAGE WAVEFORMS VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES ENABLE AND DISABLE TIMES** INVERTING AND NONINVERTING OUTPUTS LOW- AND HIGH-LEVEL ENABLING

PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 All input pulses are supplied by agreement to following absorption DRP < 10 MHz 72 = 50.0 t < 25 pc t < 25 pc
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV245DBLE	OBSOLETE	SSOP	DB	20	TBD	Call TI	Call TI
SN74LV245DW	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
SN74LV245DWR	OBSOLETE	SOIC	DW	20	TBD	Call TI	Call TI
SN74LV245PWLE	OBSOLETE	TSSOP	PW	20	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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